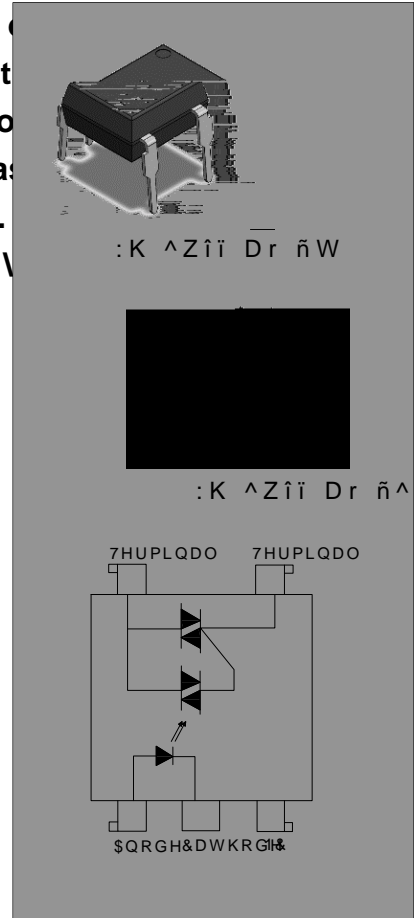




59 o/k Lt u L \ b

The products are 5-pin solid-state relay opto-couplers. The device combines an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo triac to drive a power triac in a plastic DIP5 package with different lead form options. The products are widely used in solenoid/valve controls, lighting controls, motor controls, temperature controls, static AC power switches, solid state relays, interfacing microprocessors to 265V peripherals.



5000 Vrms

DC input / triac output

Operating temperature range -40 °C to 110 °C

REACT / RoS compliance

BM: 3B / MM: M4 / CDM: C3

CEC approved

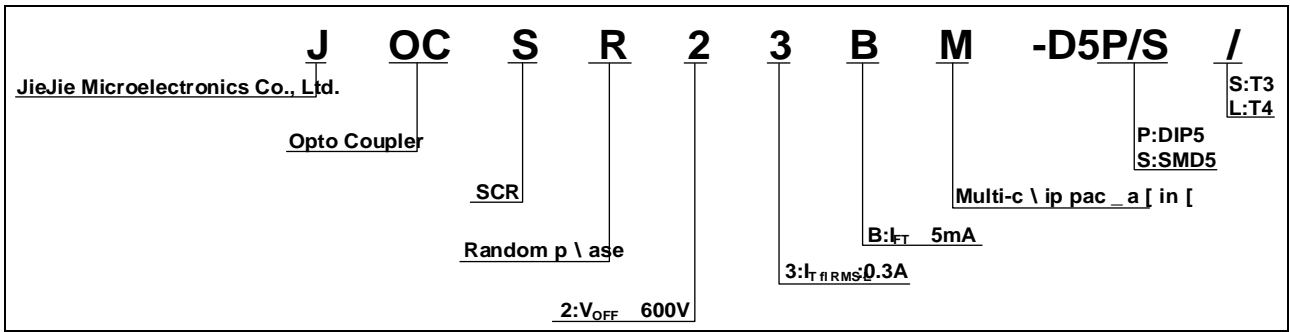
VDE approved

UL approved

Temperature Derating

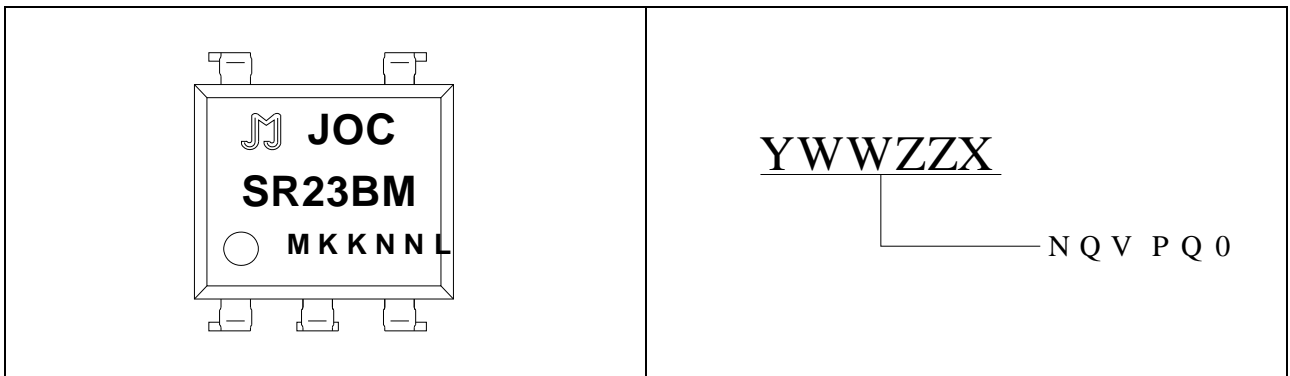
Parameter		Symbol	Value	Unit
Input	Forward Current	I_F	50	mA
	Peak Forward Current	I_{FP}	1	A
	Reverse Voltage	V_R	6	V
	Power Dissipation	P_D	75	mW
Output	Repetitive peak on-state voltage	V_{DRM}	600	V
	Repetitive peak reverse voltage	V_{RRM}	600	V
	Critical rate of rise of state current	di/dt	100	A/ s
	On-state RMS Current @ 80°C	$I_{T(RMS)}$	7.5	A
	100V On-state current	$I_{T(100V)}$	7.6	A
	50V On-state current	$I_{T(50V)}$	7.5	A

\ k 59 k LbD LbC \ ka ° uL \ b



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FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

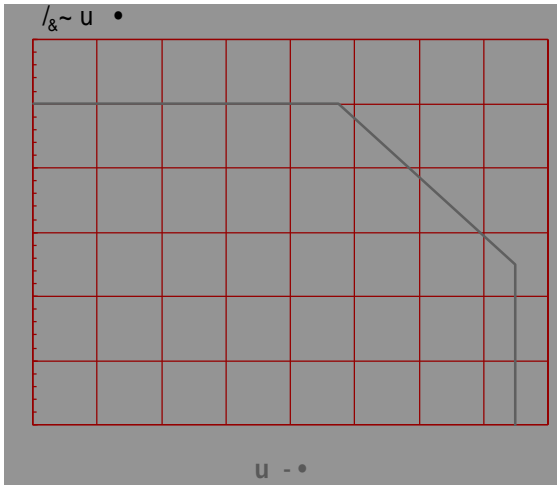


FIG.2: On-state Terminal Current vs. Ambient Temperature

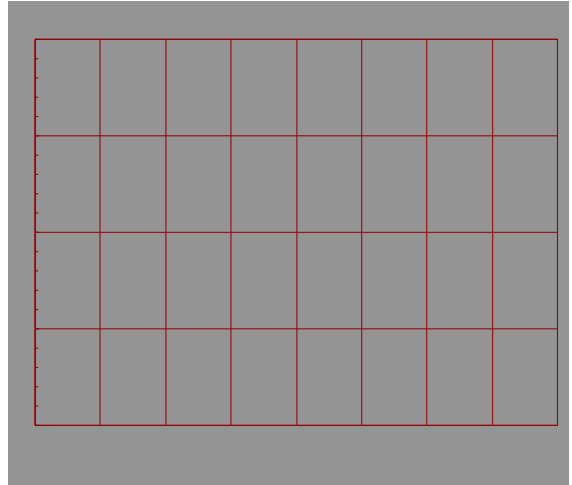


FIG.7: On-state characteristics

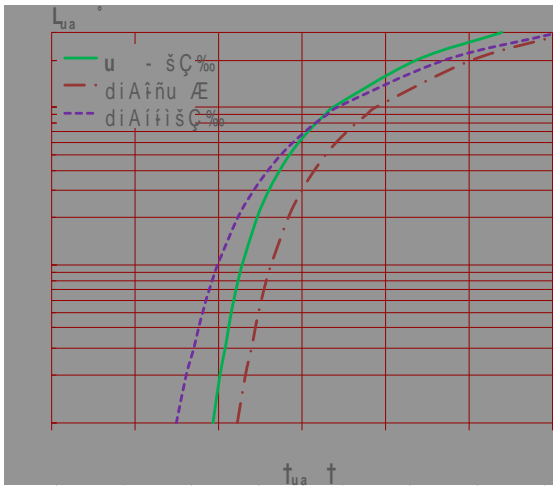


FIG.8: Normalized θ_{JA} [Current vs. Ambient Temperature

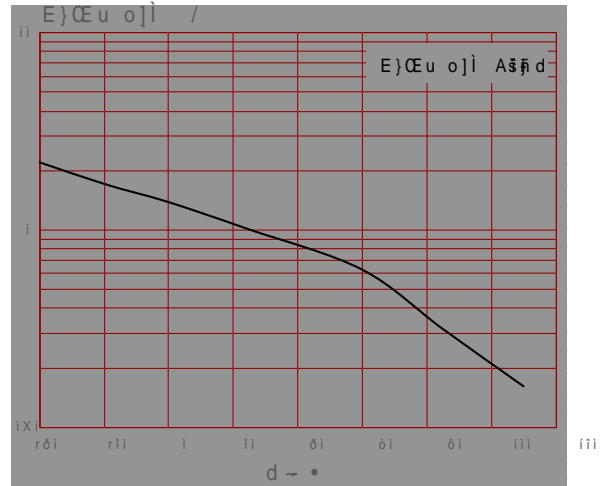
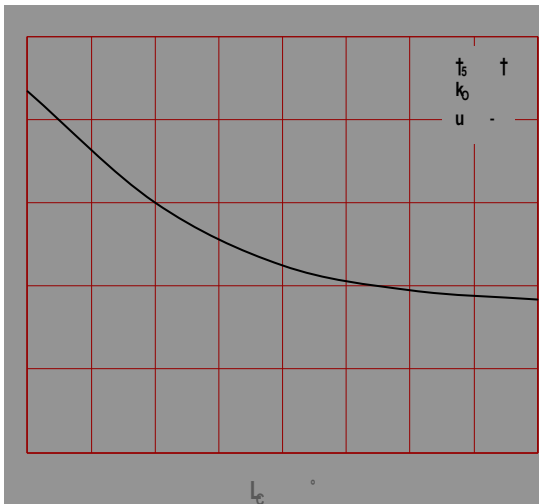


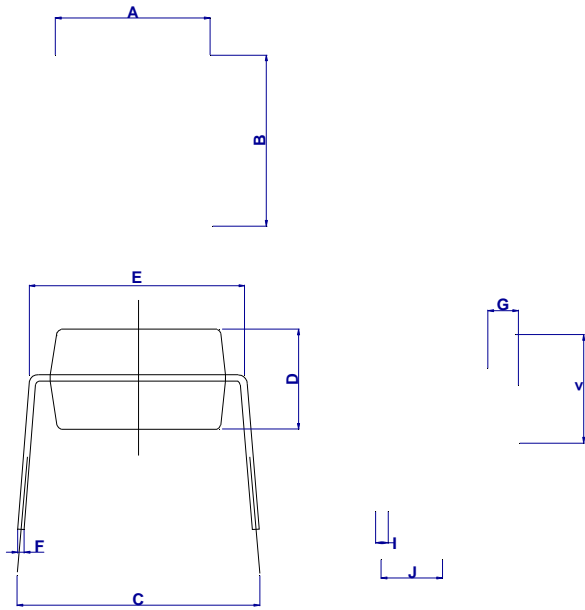
FIG.9: Turn On Time vs. Forward Current



t 5

y

Standard DIP Type:



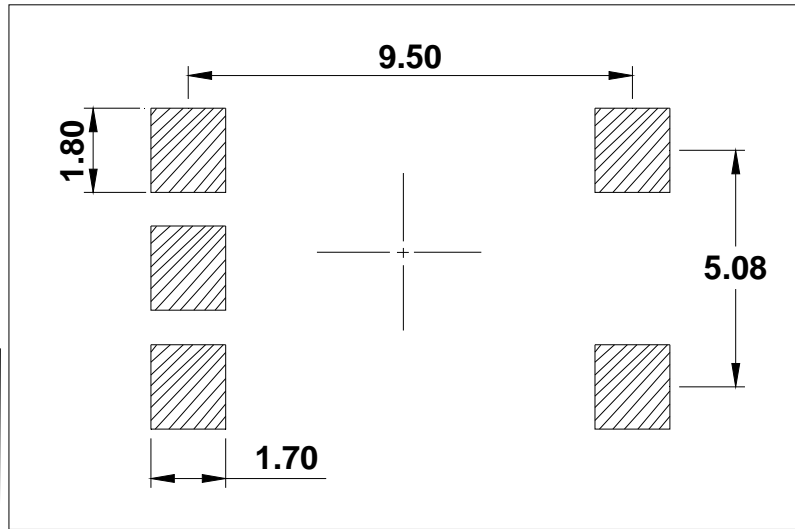
Dimensions

Millimeters

Inch

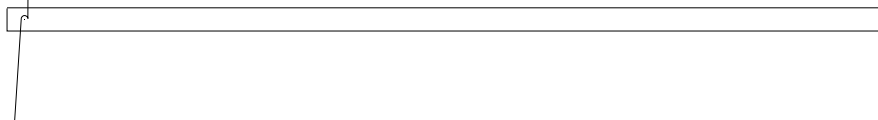
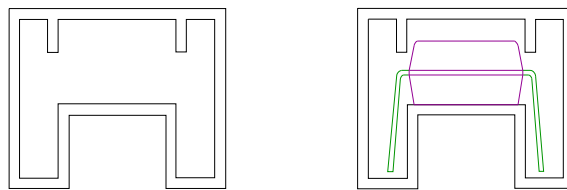
k 9/ \ aa9b595 o \ O59 k a ° o M 5

Option SMD

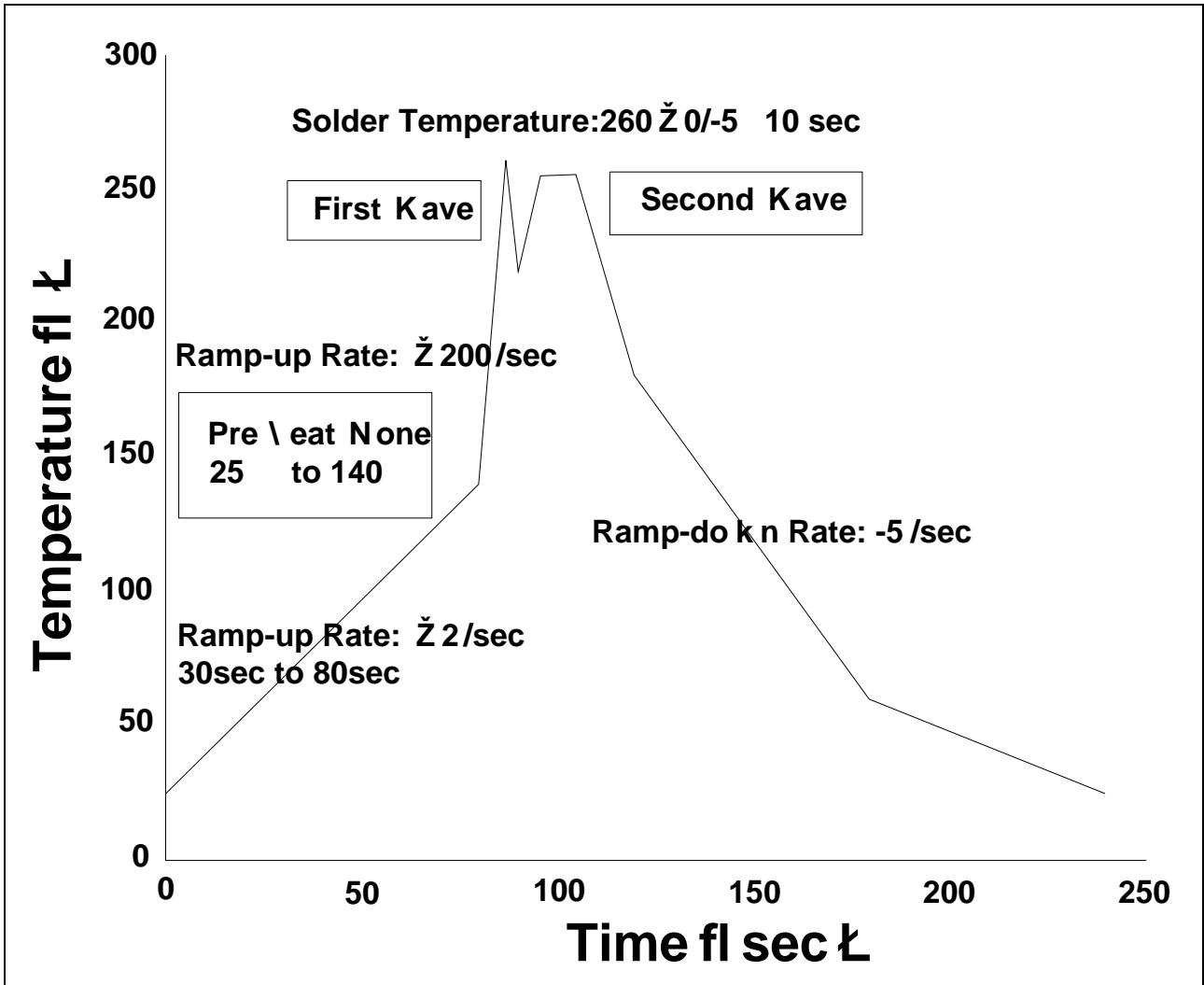


u y .9 ot9/LCL/ ° uL \ bo 5

Standard DIP



‡ ° †9 o \ O59 k LbD



I ° b5 o \ O59 k LbD . ' o \ O59 k LbD L k \ b	
Solderin [Temperature	360w5
Solderin [Time	3s max.



Note:

1. Re Z lo k solderin [is recommended at t \ e temperatures and times s \ o k n, no more t \ ree times.
2. Avoid direct contact bet k e e n \ e epoxy body and any tools osur Z aces exceedin [its maximum stora [e temperature.
3. Applicatio n o Z p r e s s u r e on t \ e epoxy body s s o n v a [A